

		Subclass	ISSUE CLASSIFICATION
		Class	

PATENT NUMBER

U.S. **UTILITY** Patent Application

O.I.P.E. SCANNED <u>11/11/2011</u> Q.A. <u>A.G.</u>	PATENT DATE
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APPLICATION NO. 09/715000	CONT/PRIOR F	CLASS 257 438	SUBCLASS 780	ART UNIT 2811 2825	EXAMINER Luu
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APPLICANTS

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Hiroaki Tomimori

TITLE

Improved semiconductor wafer surface and method of treating a semiconductor wafer surface

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PTO-2040
12/89

438/687

4381

ISSUING CLASSIFICATION

[illegible]

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) (Date)		NOTICE OF ALLOWANCE MAILED	
	<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____		ISSUE FEE	
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